# RICOH

# R5115x-Y Series

# 42 V System Power Supply with Ultra-low Power Window-type Watchdog Timer for Industrial Application

No. EY-409-190711

#### OVERVIEW

The R5115x is a system power supply IC with an ultra-low power window-type watchdog timer (VR + VD + WDT) that has an input voltage range of 3.5 V to 42 V. This is a high-reliability semiconductor device for industrial application (-Y) that has passed both the screening at high temperature and the reliability test with extended hours.

#### **KEY BENEFITS**

- Consists of a voltage regulator, a voltage detector and a watchdog timer that provides a system power supply, a
  power supply voltage monitoring and a system malfunction monitoring.
- Equipped with an auto monitoring stop (1) to cease the watchdog timer monitoring at light load.
- Outputs a reset signal from watchdog timer when a pulse signal period is too short or too long.

#### KEY SPECIFICATIONS

- Input Voltage Range (Absolute Maximum Rating):
   3.5 V to 42.0 V (50.0 V)
- Supply Current: Typ. 8.5 μA
- Protections: Thermal Shutdown, Output Current Limiting, Short-circuit Current Limiting

#### Voltage Regulator (VR) Section

- Output Voltage Range: 3.3 V to 5.0 V
- Output Voltage Accuracy: ±1.6% (-40°C ≤ Ta ≤ 125°C)
- Output Current: 250 mA

#### Voltage Detector (VD) Section

- Detection Voltage Threshold Range: 2.5 V to 4.8 V
- Detection Voltage Accuracy: ±1.6% (-40°C ≤ Ta ≤ 125°C)

#### Watchdog Timer (WDT) Section

Watchdog Timer Accuracy (tow): -17.8% to 21.7%
 (-40°C ≤ Ta ≤ 125°C)

#### **PACKAGES**

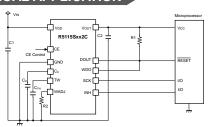


#### HSOP-8E 5.2 x 6.2 x 1.6\* mm \*maximum dimension



HSOP-18 5.2 x 6.2 x 1.6\* mm \*maximum dimension

#### TYPICAL APPLICATION



 $C_{IN}$ ,  $C_{OUT}$ : 0.1  $\mu$ F, Ceramic capacitor  $C_{TW}$ : Capacitor for setting watchdog timer  $C_D$ : Capacitor for setting reset delay time

#### SELECTION GUIDE

Product Name	Package	Quantity per Reel
R5115Sxx1*-E2-YE	HSOP-8E	1,000 pcs
R5115Sxx2*-E2-YE	HSOP-18	1,000 pcs

xx: Set output voltage ( $V_{\text{SET}}$ ) and set detection voltage ( $-V_{\text{DSET}}$ ) options. Assign a code starting from 01 to designate a desired combination of  $V_{\text{SET}}$  and  $-V_{\text{DSET}}$ .

#### \*: Other functional options

	* Package WADJ		WDO Pin	RESETB/DOUT Pin	
	Α	HSOP-8E	Fixed (2)	No	RESETB
	В	HSOP-8E	No	No	RESETB
	С	HSOP-18	Adjustable (3)	Yes	DOUT

#### **APPLICATIONS**

- Factory Automation Equipment, Smart meters
- Surveillance Camera, Vending Machines

<sup>(1)</sup> R5115Sxx1A, R5115Sxx2C only

<sup>(2)</sup> Internally fixed

<sup>(3)</sup> Adjustable using the WADJ pin

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#### **SELECTION GUIDE**

A set detection voltage, a package type, a WADJ function, a WDO pin and a RESETB/DOUT pin are user-selectable options.

#### **Selection Guide**

Product Name	Package	Quantity per Reel	Pb Free	Halogen Free
R5115Sxx1*-E2-YE	HSOP-8E	1,000 pcs	Yes	Yes
R5115Sxx2*-E2-YE	HSOP-18	1,000 pcs	Yes	Yes

xx: Set output voltage ( $V_{SET}$ ) and set detection voltage ( $-V_{DSET}$ ) options Assign a code starting from 01 to designate a desired combination of  $V_{SET}$  and  $-V_{DSET}$ .

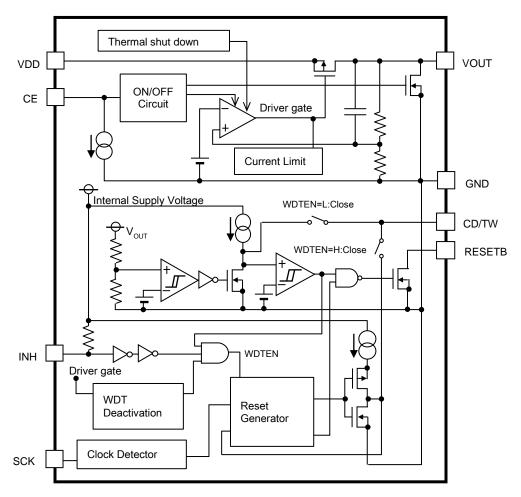
#### \*: Other functional options

*	Package	WDT Type	WADJ Function	WDO Pin	RESETB/DOUT Pin
Α	HSOP-8E	Window	Fixed <sup>(1)</sup>	No	RESETB
В	HSOP-8E	Window	No	No	RESETB
С	HSOP-18	Window	Adjustable <sup>(2)</sup>	Yes	DOUT

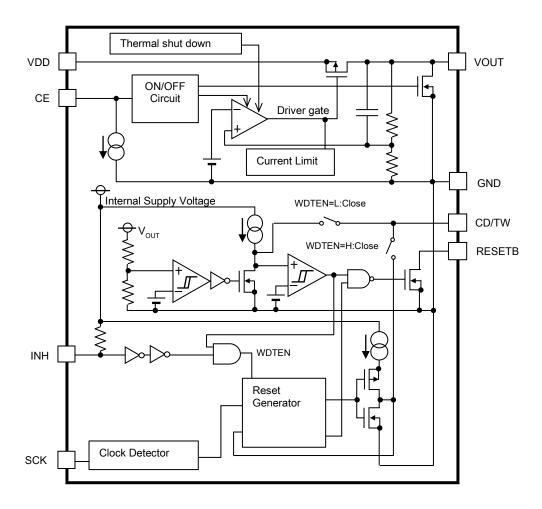
<sup>(1)</sup> internally fixed

<sup>(2)</sup> adjustable using the WADJ pin

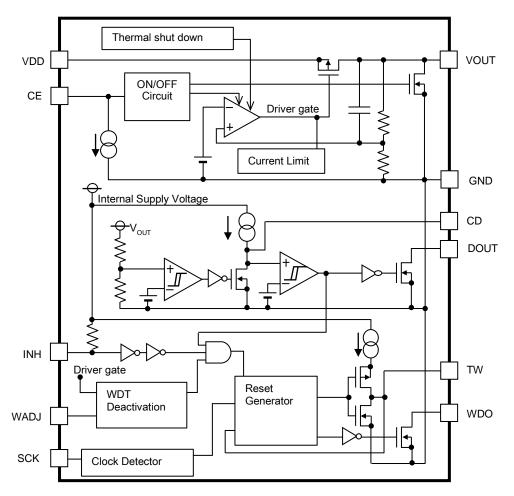
# **BLOCK DIAGRAMS**



R5115Sxx1A Block Diagram

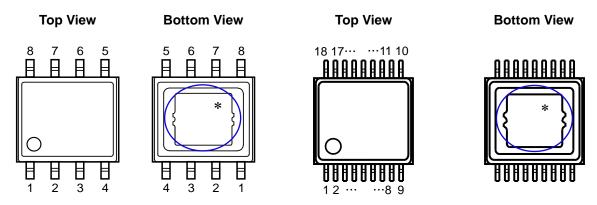


R5115Sxx1B Block Diagram



R5115Sxx2C Block Diagram

## **PIN DESCRIPTION**



**HSOP-8E Pin Configuration** 

**HSOP-18 Pin Configuration** 

HSOP-8E Pin Description, R5115Sxx1A/R5115Sxx1B

Pin No.	Pin Name	Description
1	VDD	Power Supply Pin
2	CD/TW	Watchdog Timer Monitoring Time Setting Pin/ Voltage Detector Reset Delay Time (Power-on Reset Time) Setting Pin
3	CE	Chip Enable Pin, Active-high
4	GND	Ground Pin
5	INH	Inhibit Pin, Active-low
6	SCK	Watchdog Timer Pulse Inputting Pin
7	RESETB <sup>(1)</sup>	Reset Output Pin, Active-low, Nch Open Drain Output
8	VOUT	Voltage Regulator Output Pin

<sup>\*</sup> The tab on the bottom of the package shown by blue circle is a substrate potential (GND). It is recommended that this tab be connected to the ground plane on the board but it is possible to leave the tab floating.

<sup>(1)</sup> The RESET pin voltage should be pulled up to the appropriate level using an external resistor.

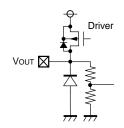
HSOP-18 Pin Description, R5115Sxx2C

Pin No.	Pin Name	Description
1	VDD	Power Supply Pin
2	NC	No Connection
3	CD	Voltage Detector Reset Delay Time (Power-on Reset Time) Setting Pin
4	NC	No Connection
5	TW	Watchdog Timer Monitoring Time Setting Pin
6	NC	No Connection
7	CE	Chip Enable Pin, Active-high
8	NC	No Connection
9	GND	Ground Pin
10	WADJ	Watchdog Timer Operating Threshold Pin
11	INH	Inhibit Pin, Active-low
12	NC	No Connection
13	SCK	Watchdog Timer Pulse Input Pin
14	NC	No Connection
15	WDO <sup>(1)</sup>	Watchdog Timer Output Pin, Nch Open Drain Output
16	DOUT <sup>(2)</sup>	RESET Output Pin, Active-low, Nch Open Drain Output
17	NC	No Connection
18	VOUT	Voltage Regulator Output Pin

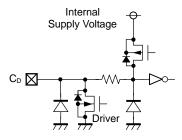
<sup>(1)</sup> The WDO pin voltage should be pulled up to the appropriate level using an external resistor. (2) The DOUT pin voltage should be pulled up to the appropriate level using an external resistor.

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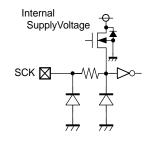
#### **Equivalent Circuits of Individual Pins**



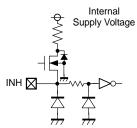
#### **Equivalent Circuit for VOUT Pin**



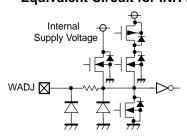
### **Equivalent Circuit for CD Pin**



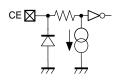
#### **Equivalent Circuit for SCK Pin**



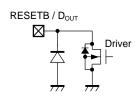
#### **Equivalent Circuit for INH Pin**



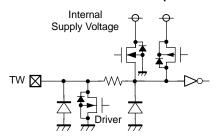
**Equivalent Circuit for WADJ Pin (R5115Sxx2C)** 



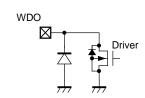
#### **Equivalent Circuit for CE Pin**



#### Equivalent Circuit for RESETB Pin (R5115Sxx1x)/ Equivalent Circuit for DOUT Pin (R5115Sxx2C)



#### **Equivalent Circuit for TW Pin**



**Equivalent Circuit for WDO Pin (R5115Sxx2C)** 

# **ABSOLUTE MAXIMUM RATINGS**

#### **Absolute Maximum Ratings**

Symbol		Paran	neter	Rating	Unit
V/	Input Voltage			-0.3 to 50	V
Vin	Peak Voltage(1)			60	V
Vce	CE Pin Input Vo	oltage	-0.3 to 50	V	
Vout	VOUT Pin Outp	ut Voltage		$-0.3$ to $V_{IN} + 0.3 \le 50$	V
V <sub>CD</sub>	CD Pin Output	Voltage		-0.3 to 7.0	V
V <sub>TW</sub>	TW Pin Output Voltage			-0.3 to 7.0	V
V <sub>RESETB</sub>	RESETB Pin Output Voltage			-0.3 to 7.0	V
V <sub>DOUT</sub>	DOUT Pin Output Voltage			-0.3 to 7.0	V
$V_{WDO}$	WDO Pin Output Voltage			-0.3 to 7.0	V
Vsck	SCK Pin Input \	/oltage		-0.3 to 7.0	V
VINH	INH Pin Input V	oltage		-0.3 to 7.0	V
$V_{WADJ}$	WADJ Pin Outp	out Voltage		-0.3 to 7.0	V
I <sub>RESETB</sub>	RESETB Pin C	urrent		16	mA
I <sub>DOUT</sub>	DOUT Pin Curr	ent		16	mA
I <sub>WDO</sub>	WDO Pin Curre	ent		16	mA
	Power (2)	HSOP-8E	JEDEC STD. 51-7	3600	\/
$P_D$	Dissipation	HSOP-18	JEDEC STD. 51-7	3900	mW
Tj	Junction Tempe	rature Range		-40 to 150	°C
Tstg	Storage Temper	ature Range		-55 to 150	°C

#### **ABSOLUTE MAXIMUM RATINGS**

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause permanent damage and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings are not assured.

<sup>(1)</sup> Application time is 200 ms or less. (2) Refer to *POWER DISSIPATION* for detailed information

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# **RECOMMENDED OPERATING CONDITIONS**

#### **Recommended Operating Conditions**

Symbol	Parameter	Rating	Unit
$V_{\text{IN}}$	Input Voltage	3.5 to 42.0	V
V <sub>CE</sub>	CE Pin Input Voltage	0 to 42.0	V
Vsck	SCK Pin Input Voltage	0 to 5.5	V
VINH	INH Pin Input Voltage	0 to 5.5	V
Та	Operating Temperature Range	-40 to 125	°C

#### **RECOMMENDED OPERATING CONDITIONS**

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

### **ELECTRICAL CHARACTERISTICS**

 $C_{\text{IN}} = C_{\text{OUT}} = 0.1 \mu \text{F}$ ,  $V_{\text{IN}} = 14 \text{ V}$ , unless othrewise noted.

The specifications surrounded by  $\square$  are guaranteed by design engineering at  $-40^{\circ}$ C  $\leq$  Ta  $\leq$  125 $^{\circ}$ C.

#### **R5115Sxxxx-YE Electrical Characteristics**

 $(Ta = 25^{\circ}C)$ 

Symbol	Parameter	Test Conditions/Comments	Min.	Тур.	Max.	Unit
Iss	Supply Current	I <sub>OUT</sub> = 0 mA R5115Sxx1A/ R5115Sxx2C		8.5	18	μΑ
	Supply Current	I <sub>OUT</sub> = 0 mA R5115Sxx1B		13.5	23	μΑ
Istandby	Standby Current	$V_{IN} = 42 \text{ V}, V_{CE} = 0 \text{ V}$		0.2	1.0	μΑ
I <sub>PD</sub>	CE Pull-down Constant Current	V <sub>CE</sub> = 42 V		0.2	0.6	μΑ
VCEH	CE Input Voltage, High		2.2		42	V
Vcel	CE Input Voltage, Low				1.0	V

VR Section (Ta =  $25^{\circ}$ C)

Symbol	Parameter	Test Conditions/Comments			Min.	Тур.	Max.	Unit
	Output Valtage			= 25°C	×0.994		×1.006	V
Vout	Output Voltage	Iout = 1 mA	-40	°C ≤ Ta ≤ 125°C	×0.984		×1.016	V
ΔV <sub>OUT</sub> / Δ <b>I</b> ouτ	Load Regulation		V <sub>IN</sub> = V <sub>SET</sub> + 3.0 V 1 mA ≤ I <sub>OUT</sub> ≤ 250 mA		-20	0	50	mV
\/	Dropout Voltage	$I_{OUT} = 250 \text{ mA}$ $V_{SET} = 3.3$ $V_{SET} = 5.0$		V <sub>SET</sub> = 3.3		1.0	2.0	V
$V_{DIF}$	Dropout Voltage				0.80	1.5	V	
$\Delta V_{OUT}/$ $\Delta V_{IN}$	Line Regulation	$3.5 \text{ V} \le \text{V}_{\text{SET}} + 0.5 \text{ V} \le \text{V}_{\text{IN}} \le 42 \text{ V}$ Iout = 1  mA				0.01	0.02	%/V
I <sub>LIM</sub>	Output Current Limit	V <sub>IN</sub> = V <sub>SET</sub> + 3	3.0 V		320	440	530	mA
Isc	Short-circuit Current Limit	V <sub>IN</sub> = 5 V, V <sub>OUT</sub> = 0 V			70	95	135	mA
T <sub>TSD</sub>	Thermal Shutdown Temperature Threshold, rising	Junction Temperature			150	170		°C
T <sub>TSR</sub>	Thermal Shutdown Temperature Threshold, falling	Junction Ten	npera	iture	125	140		°C

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= $C_{OUT}$ = 0.1 $\mu$ F, $V_{IN}$ = 14 V, unless othrewise noted.	
e specifications surrounded by are guaranteed by design engineering at −40°C ≤ Ta ≤ 125°C.	

# R5115Sxxxx-YE Electrical Characteristics (Contimued) VD Section

VD Section	on					(Ta =	: 25°C)
Symbol	Parameter	Test Condi	Min.	Тур.	Max.	Unit	
V	Detection Voltage	V <sub>DD</sub> = V <sub>OUT</sub>	Ta = 25°C	x0.994		x1.006	V
-V <sub>DET</sub>	Detection Voltage	(Vout Detection)	-40°C ≤ Ta ≤ 125°C	x0.984		x1.016	V
V <sub>HYS</sub>	Detection Threshold Hysteresis			-V <sub>DSET</sub> ×0.015		-V <sub>DSET</sub> ×0.025	V
treset	Reset Delay Time (Power-on Reset)	C <sub>D</sub> = 0.22 μF	184	220	253	ms	
$V_{RESETB}$	RESETB Pull-up Voltage	R5115Sxx1A/			5.5	V	
V <sub>DOUT</sub>	DOUT Pull-up Voltage	R5115Sxx2C			5.5	V	
IOUTRSTB	Nch Driver Output Current (RESETB Output Pin)		R5115Sxx1A / R5115Sxx1B V <sub>IN</sub> = 3.5 V, V <sub>RESETB</sub> = 0.1 V				mA
I <sub>LEAKRSTB</sub>	Nch Driver Leakage Current (RESETB Output Pin)		R5115Sxx1A / R5115Sxx1B V <sub>RESETB</sub> = 5.5 V			0.3	μΑ
Іоитроит	Nch Driver Output Current (DOUT Output Pin)	R5115Sxx2C $V_{IN} = 3.5 \text{ V}, V_{DO}$	0.3	0.6		mA	
ILEAKDOUT	Nch Driver Leakage Current (DOUT Output Pin)	R5115Sxx2C $V_{DOUT} = 5.5 V$				0.3	μΑ
RLCD	CD Auto-discharge (Nch Tr. On-resistance)	V <sub>CE</sub> = 0 V, V <sub>CD</sub>	= 0.1 V		7.5	20	kΩ

 $C_{\text{IN}} = C_{\text{OUT}} = 0.1 \mu \text{F}, \ V_{\text{IN}} = 14 \ \text{V}, \ \text{unless othrewise noted}.$  The specifications surrounded by \_\_\_\_\_\_ are guaranteed by design engineering at  $-40 \,^{\circ}\text{C} \leq \text{Ta} \leq 125 \,^{\circ}\text{C}.$ 

#### **R5115Sxxxx-YE Electrical Characteristics (Contimued)**

WDT Section (Ta = 25°C)

WDI Sectio	11				(ια-	= 23 ()
Symbol	Parameter	Test Conditions/Comments	Min.	Тур.	Max.	Unit
tow	Open Window Time	C <sub>TW</sub> = 10 nF	14.8	18.0	21.9	ms
tcw	Closed Window Time	C <sub>TW</sub> = 10 nF	3.8	4.5	5.3	ms
towL	Long Open Window Time	C <sub>TW</sub> = 10 nF	37	80	150	ms
tign	Pulse Ignoring Time	C <sub>TW</sub> = 10 nF	14.0	18.0	22.9	ms
twR	Reset Time	C <sub>TW</sub> = 10 nF	7.2	9.0	10.7	ms
Vsckh	SCK Input, High		1.5		5.5	V
Vsckl	SCK Input, Low		0		0.65	V
Vinhh	INH Input, High		1.5		5.5	V
VINHL	INH Input, Low		0		0.5	V
I <sub>INH</sub>	INH Pull-up Current	V <sub>INH</sub> = 0 V	4.0	8.0	11.5	μA
IOWDTACT	WDT Activating Threshold Current	R5115Sxx1A		1.2	2.2	mA
IOWDTDEACT	WDT Deactivating Threshold Current	R5115Sxx1A	0.6	1.0		mA
$\frac{I_{OUT}}{I_{WADJ}}(1)$	WADJ Pin Current Ratio (WDT is not active.)	R5115Sxx2C VwadJ = 0 V, lout = 10 mA	1000	1600	3200	-
$\frac{I_{OUT}}{I_{WADJ}}(2)$	WADJ Pin Current Ratio (WDT is active.)	R5115Sxx2C VwadJ=1.0 V, lout = 10 mA	800	1200	2400	-
$V_{WADJ\_TH}$	WADJ Pin Threshold Voltage	R5115Sxx2C	0.6	0.7	8.0	V
tsckwh	SCK Minimum Input Pulse Width, High	V <sub>SCKL</sub> = 0.5, V <sub>SCKH</sub> = 1.6	500			ns
tsckwl	SCK Minimum Input Pulse Width, Low	V <sub>SCKL</sub> = 0.5, V <sub>SCKH</sub> = 1.6	1500			ns
$V_{WDO}$	WDO Pull-up Voltage				5.5	V
Іоитwdo	Nch Driver Output Current (WDO Output Pin)	R5115Sxx2C V <sub>IN</sub> = 3.5 V, V <sub>WDO</sub> = 0.1 V	0.7	1.5		mA
ILEAKWDO	Nch Driver Leakage Current (WDO Output Pin)	R5115Sxx2C V <sub>WDO</sub> = 5.5 V			0.3	μΑ
R <sub>LTW</sub>	C <sub>TW</sub> Auto-discharge (Nch Tr. On-resistance)	$V_{CE} = 0 \text{ V}, V_{TW} = 0.1 \text{ V}$		7.5	20	kΩ

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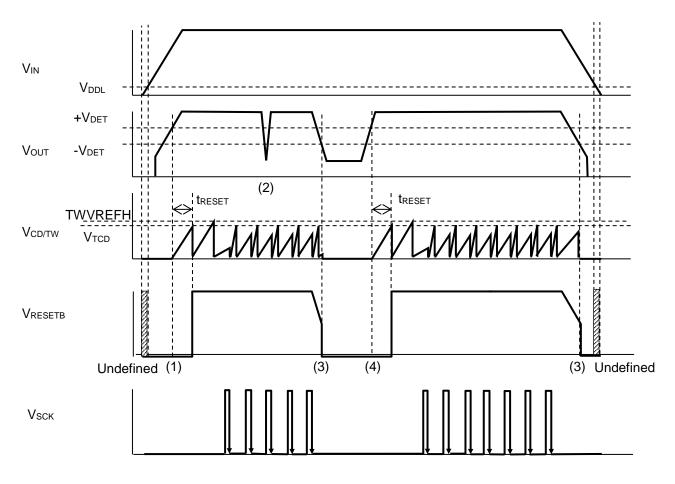
**Product-specific Electrical Characteristics: Voltage Regulator Section** 

	VR Section							
Due doet News	V <sub>OUT</sub>							
Product Name		Га = 25°C		-40 ≤ Ta ≤ 125°C				
	Min	Тур.	Max.	Min.	Тур.	Max.		
R5115S01xx	4.9700	5.000	5.0300	4.9200	5.000	5.0800		
R5115S02xx	4.9700	5.000	5.0300	4.9200	5.000	5.0800		
R5115S03xx	4.9700	5.000	5.0300	4.9200	5.000	5.0800		
R5115S04xx	4.9700	5.000	5.0300	4.9200	5.000	5.0800		
R5115S05xx	3.2802	3.300	3.3198	3.2472	3.300	3.3528		
R5115S06xx	3.2802	3.300	3.3198	3.2472	3.300	3.3528		
R5115S07xx	3.2802	3.300	3.3198	3.2472	3.300	3.3528		
R5115S08xx	4.9700	5.000	5.0300	4.9200	5.000	5.0800		
R5115S09xx	4.9700	5.000	5.0300	4.9200	5.000	5.0800		
R5115S10xx	4.9700	5.000	5.0300	4.9200	5.000	5.0800		
R5115S11xx	4.9700	5.000	5.0300	4.9200	5.000	5.0800		

**Product-specific Electrical Characteristics: Voltage Detector Section** 

•	VD Section								
Product Name	-V <sub>DET</sub>					V			
Product Name	Ta = 25°C			-40 ≤ Ta ≤ 125°C			V <sub>HYS</sub>		
	Min.	Тур.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.
R5115S01xx	4.5724	4.600	4.6276	4.5264	4.600	4.6736	0.0690	0.0920	0.1150
R5115S02xx	3.2802	3.300	3.3198	3.2472	3.300	3.3528	0.0495	0.0660	0.0825
R5115S03xx	3.9760	4.000	4.0240	3.9360	4.000	4.0640	0.0600	0.0800	0.1000
R5115S04xx	4.4730	4.500	4.5270	4.4280	4.500	4.5720	0.0675	0.0900	0.1125
R5115S05xx	2.9820	3.000	3.0180	2.9520	3.000	3.0480	0.0450	0.0600	0.0750
R5115S06xx	2.8826	2.900	2.9174	2.8536	2.900	2.9464	0.0435	0.0580	0.0725
R5115S07xx	2.6838	2.700	2.7162	2.6568	2.700	2.7432	0.0405	0.0540	0.0675
R5115S08xx	4.3736	4.400	4.4264	4.3296	4.400	4.4704	0.0660	0.0880	0.1100
R5115S09xx	4.0754	4.100	4.1246	4.0344	4.100	4.1656	0.0615	0.0820	0.1025
R5115S10xx	4.1748	4.200	4.2252	4.1328	4.200	4.2672	0.0630	0.0840	0.1050
R5115S11xx	2.4850	2.500	2.5150	2.4600	2.500	2.5400	0.0375	0.0500	0.0625

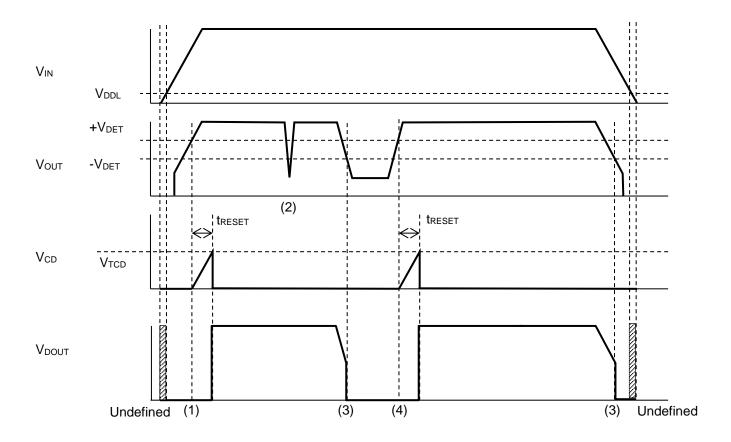
#### THEORY OF OPERATION



R5115Sxx1A/ R5115Sxx1B VD Timing Chart

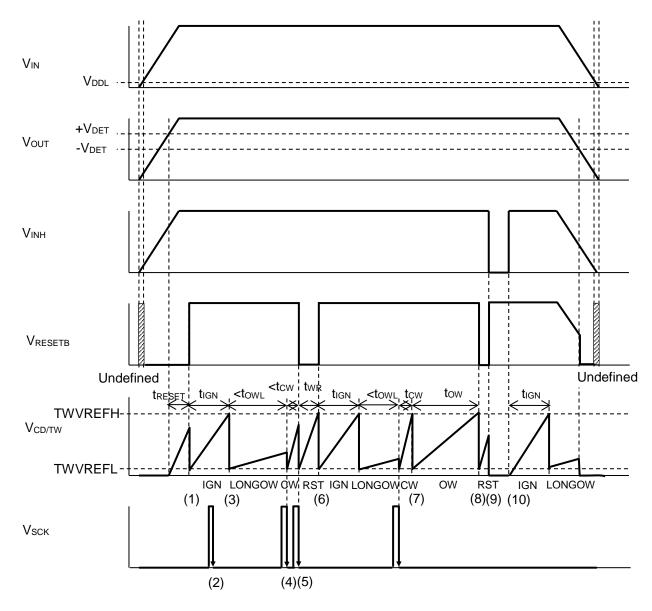
- (1) When the output voltage (Vout) of a voltage regulator (VR) becomes more than the reset voltage (+VDET), the RESETB pin voltage (VRESETB) becomes high after the reset delay time (treset). During treset, the CD/TW pin serves as a rest delay time setting pin. When VRESETB becomes high, the CD/TW pin serves as a watchdog timer setting pin.
- (2) When V<sub>OUT</sub> becomes lower than the detection voltage (-V<sub>DET</sub>) and when that period is shorter than the delay time (t<sub>DELAY</sub>), Typ. 30 μs or lower, V<sub>RESETB</sub> remains high and does not go into the detecting state.
- (3) When V<sub>OUT</sub> becomes lower than -V<sub>DET</sub>, V<sub>RESETB</sub> becomes low after a 30-µs (Typ.) t<sub>DELAY</sub>, and the voltage detector (VD) goes into the detecting state.
- (4) When V<sub>OUT</sub> becomes higher than +V<sub>DET</sub>, V<sub>RESETB</sub> becomes high after t<sub>RESET</sub>. (V<sub>TCD</sub> = Typ.1 V)

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R5115Sxx2C VD Timing Chart

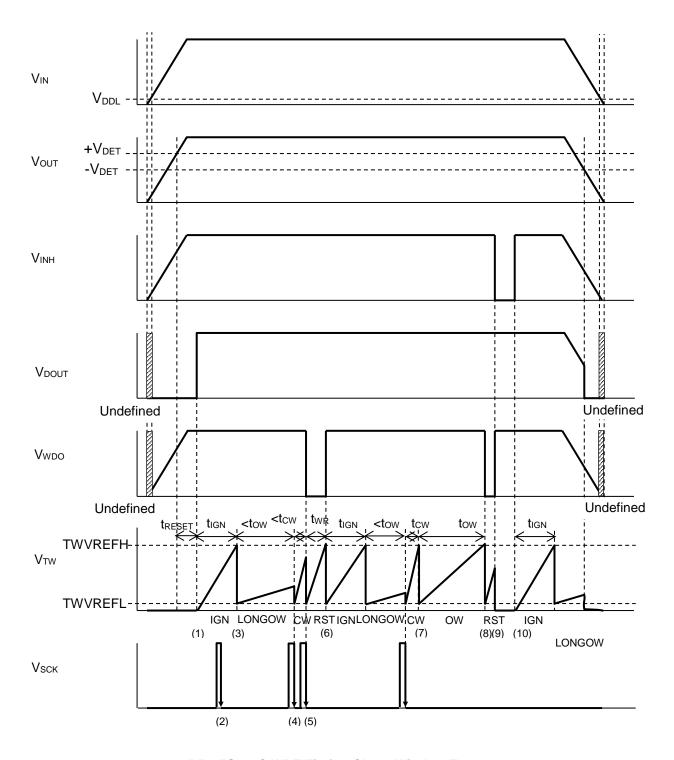
- (1) When the output voltage (V<sub>OUT</sub>) of a voltage regulator (VR) becomes higher than the reset voltage (+V<sub>DET</sub>), the DOUT pin voltage (V<sub>DOUT</sub>) becomes high after the reset delay time (t<sub>RESET</sub>).
- (2) When  $V_{OUT}$  becomes lower than the detection voltage (- $V_{DET}$ ) and when that period is shorter than the delay time ( $t_{DELAY}$ ), Typ. 30  $\mu s$  or lower,  $V_{DOUT}$  remains high and does not go into the detecting state.
- (3) When V<sub>OUT</sub> becomes lower than -V<sub>DET</sub>, V<sub>DOUT</sub> becomes low after a 30-µs (Typ.) t<sub>DELAY</sub>, and the voltage detector (VD) goes into the detecting state.
- (4) When  $V_{OUT}$  becomes higher than  $+V_{DET}$ ,  $V_{DOUT}$  becomes high after  $t_{RESET}$ . ( $V_{TCD} = Typ.1 V$ )



R5115Sxx1A/R5115Sxx1B WDT Timing Chart, Window Type

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- (1) When the output voltage (Vout) of a voltage regulator (VR) becomes higher than the reset voltage (+VDET), the RESETB pin voltage (VRESETB) becomes high after the reset delay time (treset), and the watchdog timer (WDT) starts monitoring a pulse. After that, the CD/TW pin voltage (VCD/TW) repeats charge and discharge. As a result, a sawtooth wave is generated. The WDT has four states: Ignoring, Reset, Open Window and Closed Window. In each state, the CD/TW pin is charged from 0 V or TWVREFL (Typ. 0.08 V).
- (2) After WDT starts, WDT is in an ignoring state until V<sub>CD/TW</sub> is charged up to TWVREFH (Typ. 2V). So, a pulse to the SCK pin is ignored during the ignoring state.
- (3) When V<sub>CD/TW</sub> is charged up to TWVREFH during the ignoring state, the CD/TW pin starts discharging and WDT goes into a long open window state. While this long open window state works as an open window state, it is four times longer than the normal open window state.
- (4) When a pulse is sent to the SCK pin before V<sub>CD/TW</sub> reaches TWVREFH during the open window state, the CD/TW pin starts discharging and WDT goes into a closed window state.
- (5) When a pulse is sent to the SCK pin before V<sub>CD/TW</sub> reaches TWVREFH during the closed window state, the CD/TW pin starts discharging and WDT goes into a reset state. During the reset state, V<sub>RESETB</sub> becomes low.
- (6) When V<sub>CD/TW</sub> reaches TWVREFH during the reset state, the CD/TW pin starts discharging and WDT goes into an ignoring state.
- (7) When a pulse is not sent to the SCK pin before V<sub>CD/TW</sub> reaches TWVREFH during a closed window state, the CD/TW pin starts discharging and WDT goes into an open window state.
- (8) When a pulse is not sent to the SCK pin before V<sub>CD/TW</sub> reaches TWVREFH during the open window state, the CD/TW pin starts discharging and WDT goes into a reset state.
- (9) When the INH pin voltage (V<sub>INH</sub>) is set to low, WDT stops monitoring. So, the voltage detector (VD) determines whether V<sub>RESETB</sub> is set to high/low, or V<sub>CD/TW</sub> is charged/discharged.
- (10) When V<sub>INH</sub> is changed from low to high, WDT goes into the ignoring state and restarts monitoring a pulse.

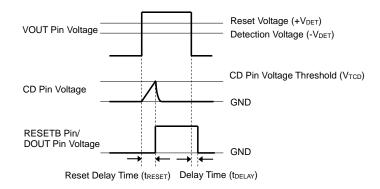


R5115Sxx2C WDT Timing Chart, Window Type

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- (1) When the output voltage (V<sub>DUT</sub>) of a voltage regulator (VR) becomes higher than the reset voltage (+V<sub>DET</sub>), the DOUT pin voltage (V<sub>DOUT</sub>) becomes high after the reset delay time (t<sub>RESET</sub>), and the watchdog timer (WDT) starts monitoring a pulse. After that, the TW pin voltage (V<sub>TW</sub>) repeats charge and discharge. As a result, a sawtooth wave is generated. WDT has four states: Ignoring, Reset, Open Window and Closed Window. In each state, the TW pin is charged from 0 V or TWVREFL (Typ.0.08 V).
- (2) After WDT starts, WDT is in an ignoring state until V<sub>TW</sub> is charged up to TWVREFH. So, a pulse to the SCK pin is ignored during the ignoring state.
- (3) When V<sub>TW</sub> is charged up to TWVREFH during the ignoring state, the TW pin starts discharging and WDT goes into a long open window state. While this long open window state works as an open window state, it is four times longer than the normal open window state.
- (4) When a pulse is sent to the SCK pin before V<sub>TW</sub> reaches TWVREFH during the open window state, the TW pin starts discharging and WDT goes into a closed window state.
- (5) When a pulse is sent to the SCK pin before V<sub>TW</sub> reaches TWVREFH during the close window state, the TW pin starts discharging and WDT goes into a reset state. During the reset state, V<sub>DOUT</sub> becomes low.
- (6) When V<sub>TW</sub> reaches TWVREFH during the reset state, the TW pin starts discharging and WDT goes into an ignoring state.
- (7) When a pulse is not sent to the SCK pin before V<sub>™</sub> reaches TWVREFH during a closed window state, the TW pin starts discharging and WDT goes into an open window state
- (8) When a pulse is not sent to the SCK pin before  $V_{TW}$  reaches TWVREFH during the open window state, the TW pin starts discharging and WDT goes into a reset state
- (9) When the INH pin voltage ( $V_{INH}$ ) is set to low, WDT stops monitoring. Then, the WDO pin voltage ( $V_{WDO}$ ) is fixed to high and  $V_{TW}$  is fixed to low.
- (10) When V<sub>INH</sub> is changed from low to high, WDT goes into the ignoring state and restarts monitoring a pulse.

#### **Delay Operation and Reset Delay Time**



RESETB Pin: R5115Sxx1A/ R5115Sxx1B

DOUT Pin: R5115Sxx2C

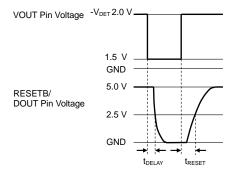
#### **Delay Time Operation Timing Chart**

When the VOUT pin voltage (Vout) becomes higher than the reset voltage (+VDET), the CD pin voltage (VCD) increases as the external capacitor starts charging. The RESETB pin voltage (VRESETB)/ the DOUT pin voltage (VDOUT) remains low until VCD reaches the CD pin voltage threshold (VTCD). When VCD becomes higher than VTCD, VRESETB or VDOUT changes from low to high. The reset delay time (tRESET) starts when the VOUT becomes higher than +VDET and ends when VDOUT/VRESETB changes from low to high. When VDOUT/VRESETB changes from low to high, the electrical charge charged in the external capacitor starts discharging. The delay time (tDELAY) starts when VOUT becomes lower than the detection voltage (-VDET) and ends when VDOUT/VRESETB changes from high to low. It is not dependent on the capacitance of the external capacitor.

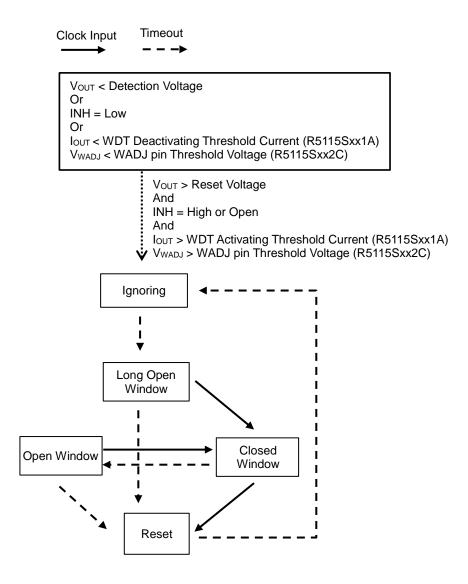
#### Method of Calculating the Reset Delay Time

The reset delay time ( $t_{RESET}$ ) can be calculated by the following equation using an external capacitance ( $C_D$ ):  $t_{RESET}$  (s) = 1.0 x  $C_D$  (F) / (1.0 x 10<sup>-6</sup>)

To make the VOUT/ SENSE pin voltage rises slower than 0.1 V/s, place a 100-pF or more capacitor ( $C_D$ ).  $t_{RESET}$  starts when the RESETB/DOUT pin is pulled up to 5 V using a 100-k $\Omega$  resistor, and a 1.5-V to (- $V_{DET}$ ) + 2.0-V pulse voltage is applied to the VOUT pin. It ends when  $V_{OUT}$  reaches 2.5 V.



#### **Watchdog Timer State Transition Diagram**



#### **Watchdog Timer Setting**

A watchdog timer (tow, tow, tow, tow, tign, twr) can be set by using a capacitor connected to the TW pin. The relationship between capacitance and time are described as below:

$$t_{OW}$$
 (s) = 1.8 x C(F) / (1.0 x 10<sup>-6</sup>)

tcw (s) = 
$$1.8 \times C(F) / (4.0 \times 10^{-6})$$

$$towL(s) = 1.8 \times C(F) / (0.225 \times 10^{-6})$$

$$t_{IGN}(s) = 1.8 \times C(F) / (1.0 \times 10^{-6})$$

$$t_{WR}(s) = 1.8 \times C(F) / (2.0 \times 10^{-6})$$

#### **Allowable SCK Pulse Period**

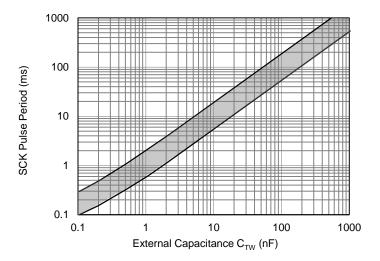
To prevent WDT of the R5115x from going into a reset state, the pulse period inputted to the SCK pin has to meet the following condition.

tcw max < SCK Pulse Period < (tcw + tow) min

The closed window time ( $t_{CW}$ ) and the open window time ( $t_{OW}$ ) in Electrical Characteristics may vary, and also the capacitor connected to the TW pin ( $C_{TW}$ ) or the CD/TW pin ( $C_D/C_{TW}$ ) may cause variations in  $t_{CW}$  or  $t_{OW}$ . Those variations are considered in the calculations below.

Min. SCK Pulse Period (s) = 0.53 x Max.  $C_{TW}$  (F) x  $10^6$  Max. SCK Pulse Period (s) = 1.86 x Min.  $C_{TW}$  (F) x  $10^6$ 

The graph below shows the relationship between the SCK pulse period and the external capacitance of  $C_{TW}$ . The pulse period inputted to the SCK pin has to be fit within the grayed-out area according to the capacitance of  $C_{TW}$ .



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#### **Standby Function**

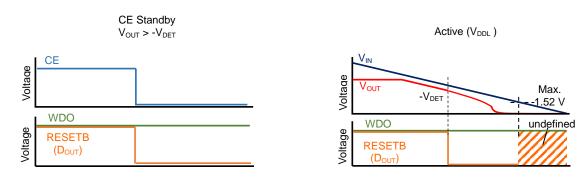
When the CE pin voltage (V<sub>CE</sub>) is low, the R5115S goes into the standby mode. During the standby mode, the voltage regulator (VR) stops the output, the watchdog timer (WDT) stops the pulse monitoring and the voltage detector (VD) stops the voltage monitoring.

When VCE is low, the outputs of WDT and VD will be as follows regardless of the output voltage (Vout).

R5115Sxx1A/ R5115Sxx1B: The RESETB pin voltage (VRESETB) is fixed to low.

R5115Sxx2C: The DOUT pin voltage (V<sub>DOUT</sub>) is low and the WDO pin voltage (V<sub>WDO</sub>) is fixed to the pull-up voltage.

When the input voltage ( $V_{IN}$ ) is less than 1.52 V with 5-V pull-up voltage and 100-k $\Omega$  pull-up resistance,  $V_{RESETB}/V_{DOUT}$  becomes indefinite, which means 0.1 V or more.



#### **Voltage Regulator Voltage Setting**

The voltage detector (VD) detects the output voltage drop of the voltage regulator (VR). If the VD reset voltage (+V<sub>DET</sub>) is set to higher than the VR output voltage (V<sub>OUT</sub>), VD continuously sends a reset signal even if VR output voltage (V<sub>OUT</sub>) returns to the normal after detecting the output voltage drop of VR. To prevent this, the following conditions have to be met.

(VR Set Output Voltage) x 0.985 - 30 mV > (VD Set Detection Voltage) x 1.018 x 1.030

When using a device that is not meeting the above conditions, careful consideration must be given to the system operation before use.

#### **Inhibit Function**

When the INH pin voltage ( $V_{INH}$ ) is low, the watchdog timer (WDT) stops monitoring a pulse. The WDO pin voltage ( $V_{WDO}$ ) is fixed to high. The INH pin voltage ( $V_{INH}$ ) is internally pulled up with a 400-k $\Omega$  (Typ.) resistor.

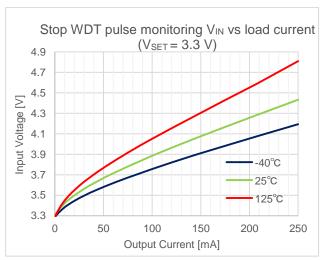
#### **WADJ Function**

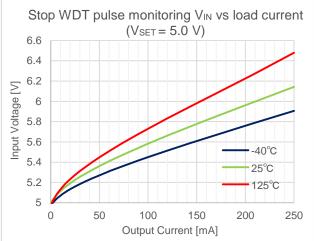
The R5115Sxx1A/ R5115Sxx2C stops monitoring a pulse when the VR load current, which is a current flowing from the VOUT pin, is small. Vwdo is fixed to high. With the R5115Sxx1A, WDT stops monitoring a pulse when the load current is 1.0 mA (Typ.). With the R5115Sxx2C, the load current can be set by using a resistor (R2) connected to the WADJ pin. The relationships between the resistance (R2) and the load current for deactivating the pulse monitoring of WDT (IOWDTDEACT), and the resistance (R2) and the load current for activating the pulse monitoring of WDT (IOWDTACT) are described as below.

$$\begin{aligned} &\text{Iowdtact} = \text{Vwadj\_th} * \frac{I_{OUT}}{I_{WADJ}}(1) \text{ / R2} \\ &\text{Iowdtdeact} = \text{Vwadj\_th} * \frac{I_{OUT}}{I_{WADJ}}(2) \text{ / R2} \end{aligned}$$

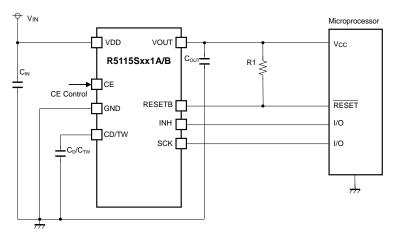
With the R5115Sxx1B, WDT monitors a pulse even when VR is in no-load state.

It is noted that WDT stops its operation regardless of load current of VR in the range of  $V_{IN}$  where the stable operation is not ensured owing to low  $V_{OUT}$ ; Dropout Voltage ( $V_{DIF}$ ):  $V_{IN}$  -  $V_{OUT}$  is < 1.2 V ( $V_{SET} = 3.3 \text{ V}$ ,  $I_{OUT} = 100 \text{ mA}$ ). The output voltage from RESETB pin of R5115Sxx1A depends on only VD and WDO pin is hold as "High."

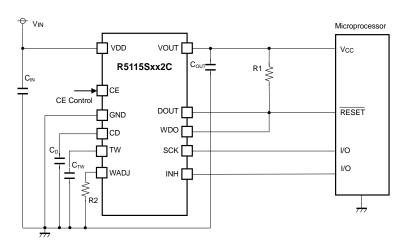




# **APPLICATION INFORMATION**



R5115Sxx1A/B Typical Application Circuit



**R5115Sxx2C Typical Application Circuit** 

**External Components** 

Symbol	Description
C <sub>IN</sub>	0.1 μF, Ceramic Capacitor
Соит	0.1 μF, Ceramic Capacitor
Стw	Capacitor for setting a WDT Refer to WDT Setting at Theory of Operation.
C <sub>D</sub>	Capacitor for setting reset delay time Refer to Delay Operation and Reset Delay Time at THEORY OF OPERATION.
R1	Set the value for R1 considering the output current when the Nch is on and the leakage current when the Nch is off described in the Electrical Characteristics.
R2	Set the value for R2 considering the WADJ pin current ration and the WADJ pin threshold voltage described in the Electrical Characteristics.

#### **TECHNICAL NOTES**

The performance of a power source circuit using this device is highly dependent on a peripheral circuit. A peripheral component or the device mounted on PCB should not exceed its rated voltage, rated current or rated power. When designing a peripheral circuit, please be fully aware of the following points.

#### **Phase Compensation**

A phase compensation is provided to secure stable operation even when the load current is varied. For this purpose, use a 0.1- $\mu$ F or more output capacitor ( $C_{OUT}$ ) with good frequency characteristics and proper ESR (Equivalent Series Resistance). In case of using a tantalum type capacitor with a large ESR, the output might become unstable. Evaluate your circuit including consideration of frequency characteristics. Connect a 0.1- $\mu$ F or more input capacitor ( $C_{IN}$ ) between the VDD and GND pins with shortest-distance wiring.

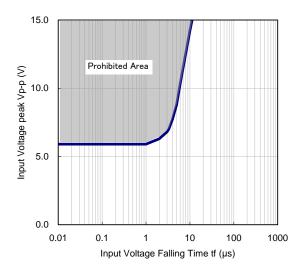
#### **PCB Layout**

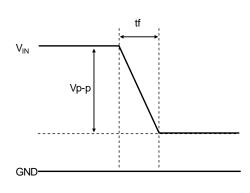
Ensure that the VDD and GND lines are sufficiently robust. If their impedances are too high, noise pickup or unstable operation may result. Connect a 1.0  $\mu$ F or more input capacitor ( $C_{IN}$ ) between the VDD and GND pins with shortest-distance wiring. Also, connect an output capacitor ( $C_{OUT}$ ) between the VOUT and GND pins with shortest-distance wiring.

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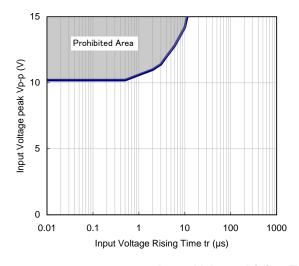
#### **Input Voltage Fluctuation Prohibited Area**

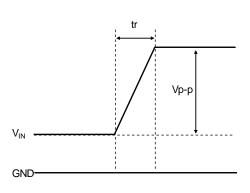
The input voltage fluctuation in the following area may cause false detection or false detection release, so should not be allowed.





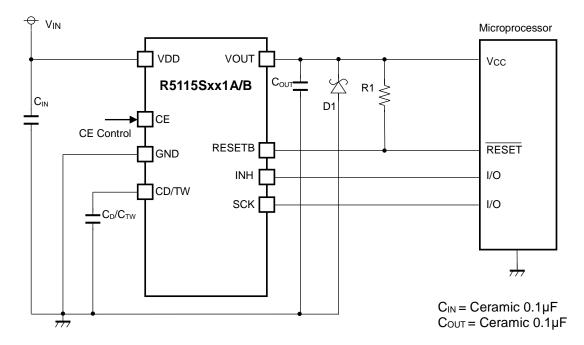
Input Voltage Falling Fluctuation Prohibited Area





Input Voltage Rising Fluctuation Prohibited Area

#### Typical Application Circuit with IC Chip Breakdown Prevention



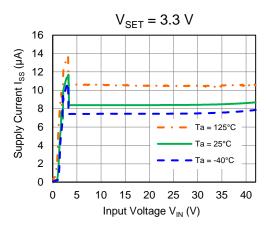
R5115Sxx1A/B Typical Application Circuit with IC Chip Breakdown Prevention

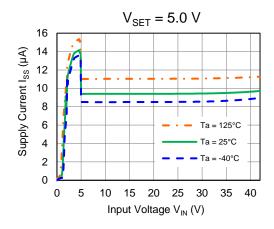
When a sudden surge of electrical current travels along the VOUT pin and GND due to a short-circuit, electrical resonance of a circuit involving an output capacitor ( $C_{OUT}$ ) and a short circuit inductor generates a negative voltage and may damage the device or the load devices. Connecting a schottky diode (D1) between the VOUT pin and GND has the effect of preventing damage to them.

## **TYPICAL CHARACTERISTICS**

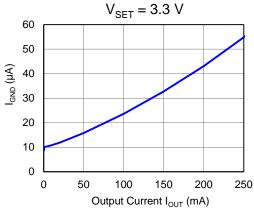
Note: Typical Characteristics are intended to be used as reference data; they are not guaranteed.

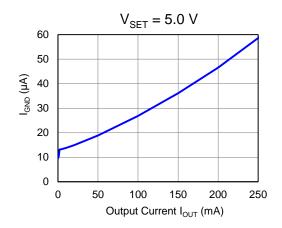
#### 1) Supply Current vs. Input Voltage



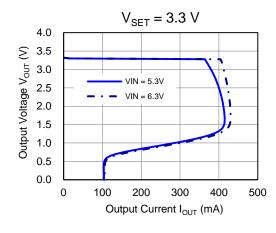


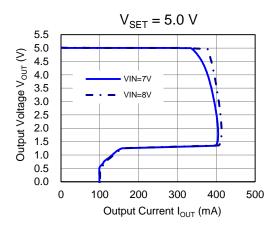
#### 2) GND Pin Current vs. Output Current (Ta = 25°C)



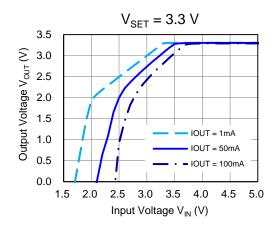


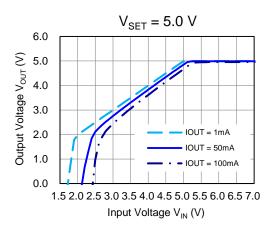
#### 3) Output Voltage vs. Output Current (Ta = 25°C)



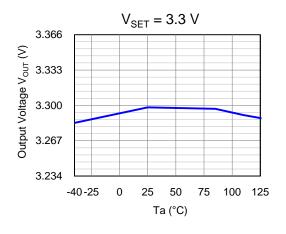


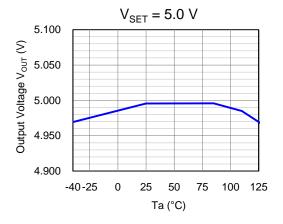
#### 4) Output Voltage vs. Input Voltage (Ta = 25°C)



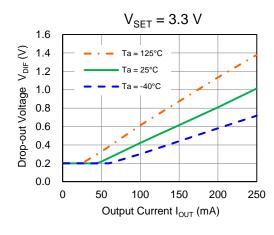


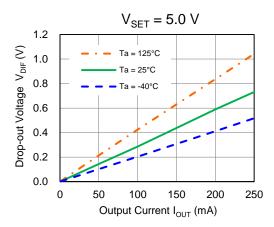
#### 5) Output Voltage vs. Ambient Temperature ( $V_{IN} = 14 \text{ V}, I_{OUT} = 1 \text{ mA}$ )



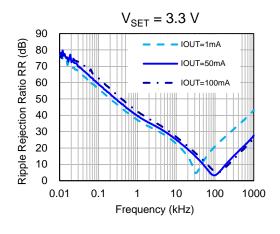


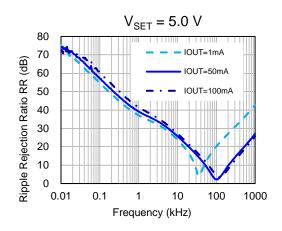
#### 6) Dropout Voltage vs. Output Current



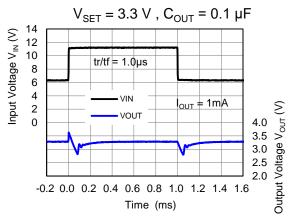


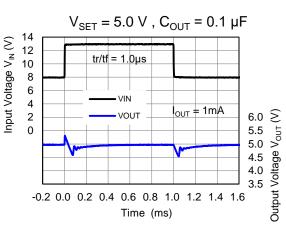
#### 7) Ripple Rejection vs. Frequency (Ta = 25°C, Ripple = 0.2 Vpp)

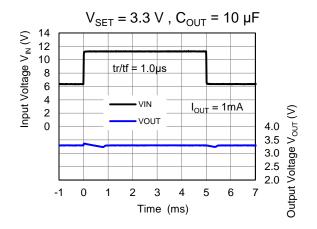


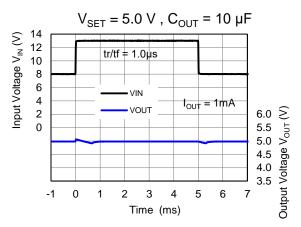


#### 8) Input Transient Response (Ta = 25°C)

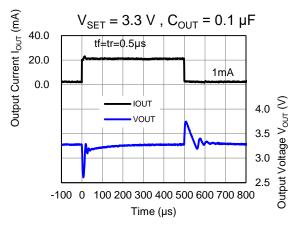


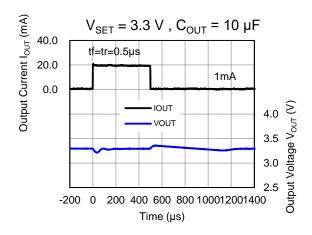


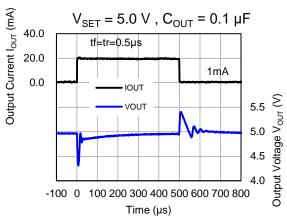


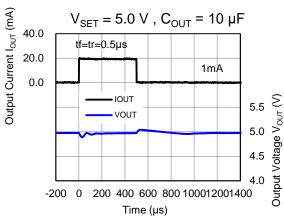


#### 9) Load Transient Response (Ta = 25°C)

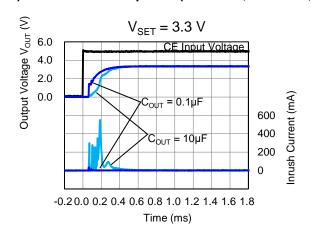


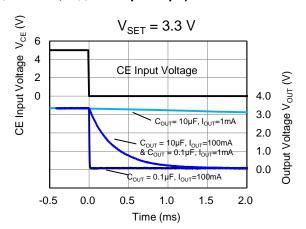




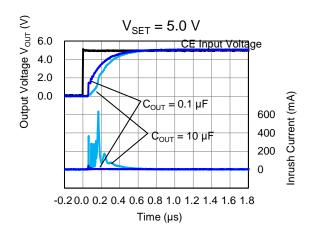


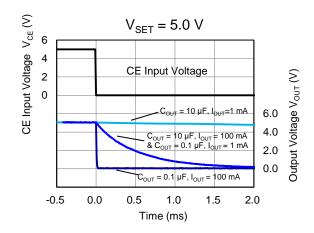
### 10) CE Transient Response (Ta = 25°C, $V_{IN}$ = 14 V, $I_{OUT}$ = 1 mA, $C_{OUT}$ = 0.1 $\mu$ F/10 $\mu$ F)



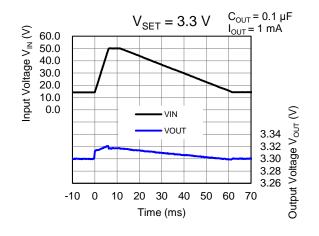


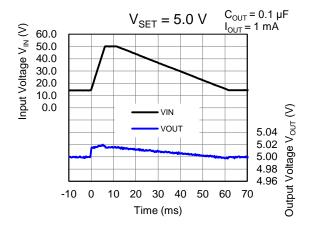
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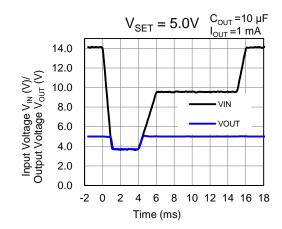


#### 11) Load Dump ( $Ta = 25^{\circ}C$ )

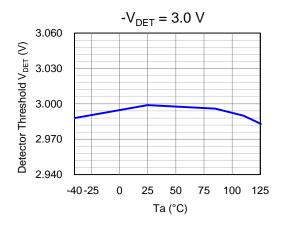


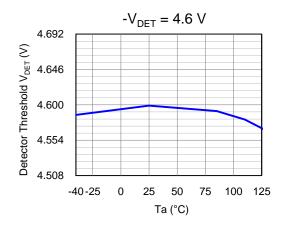


## 12) Cranking (Ta = 25°C)

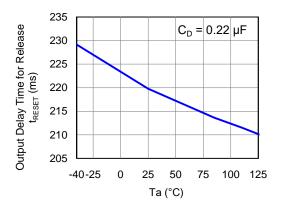


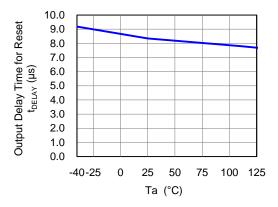
#### 13) Detection Voltage vs. Ambient Temperature



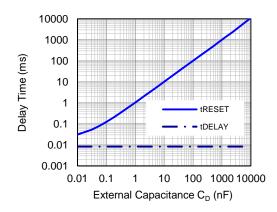


#### 14) Release Delay Time vs. Ambient Temperature 15) Detection Delay Time vs. Ambient Temperature

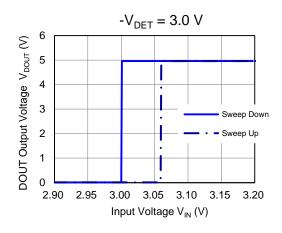


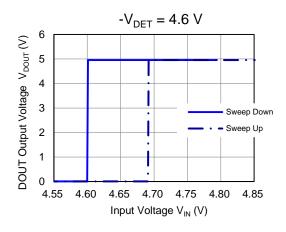


#### 16) Release Delay and Detection Delay Time vs. CD Pin External Capacitance



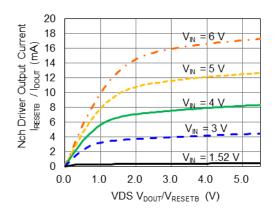
#### 17) DOUT Pin Voltage vs. Input Voltage (DOUT pulled-up to 5 V with 100 kΩ)

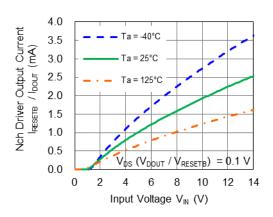




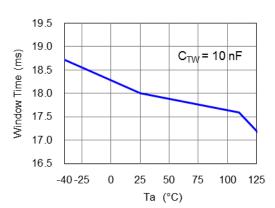
## 18) RESETB/DOUT Driver Output Current vs. V<sub>DS</sub>

19) RESETB/DOUT Driver Output Current vs. Input Voltage

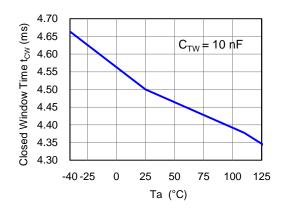




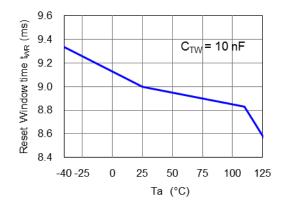
# 20) Open Window Time/Pulse Ignoring Time vs. Ambient Temperature



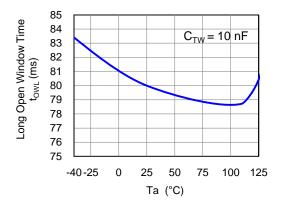
21) Closed Window Time vs. Ambient Temperature



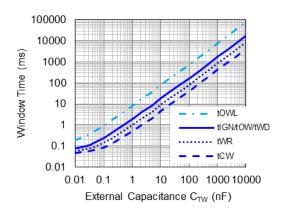
#### 22) Reset Time vs. Ambient Temperature



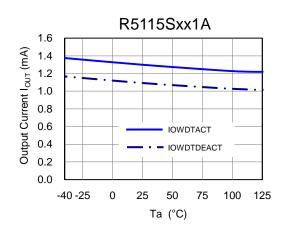
23) Long Open Window Time vs. Ambient Temperature



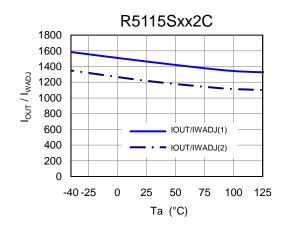
24) WDT two / tow / tcw / tign / towL / trst vs. TW Pin External Capacitance



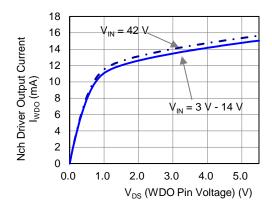
# 25) WDT Monitoring Threshold Load Current vs. Ambient Temperature



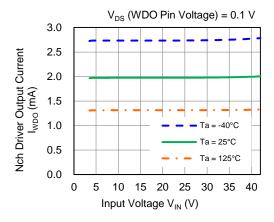
# 26) WADJ Pin Current Ratio vs. Ambient Temperature



#### 27) WDO Driver Output Current vs. $V_{\text{DS}}$



#### 28) WDO Driver Output Current vs. Input Voltage



Ver. B

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

#### **Measurement Conditions**

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.3 mm × 21 pcs

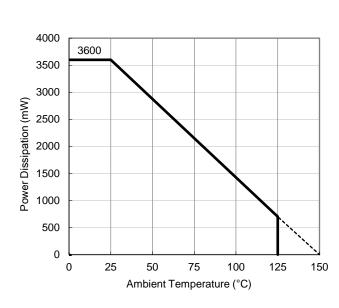
#### **Measurement Result**

 $(Ta = 25^{\circ}C, Tjmax = 150^{\circ}C)$ 

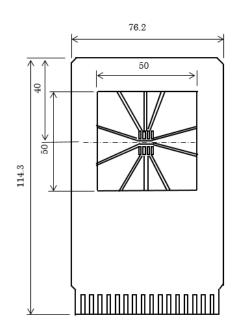
Item	Measurement Result
Power Dissipation	3600 mW
Thermal Resistance (θja)	θja = 34.5°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 10°C/W

θja: Junction-to-Ambient Thermal Resistance

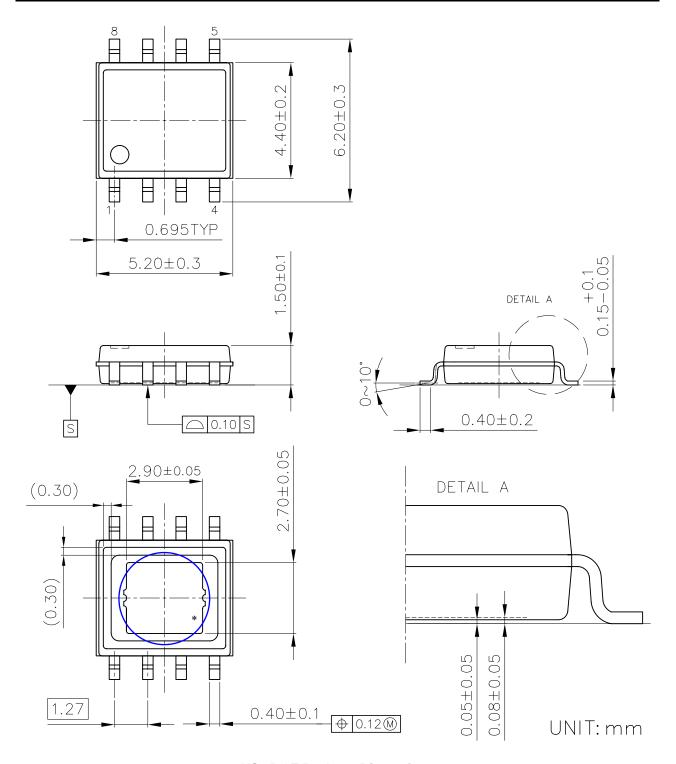
ψjt: Junction-to-Top Thermal Characterization Parameter



Power Dissipation vs. Ambient Temperature



**Measurement Board Pattern** 



**HSOP-8E Package Dimensions** 

<sup>\*</sup> The tab on the bottom of the package shown by blue circle is substrate potential (GND). It is recommended that this tab be connected to the ground plane on the board but it is possible to leave the tab floating.

Ver. B

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

#### **Measurement Conditions**

Item	Measurement Conditions			
Environment	Mounting on Board (Wind Velocity = 0 m/s)			
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)			
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm			
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square			
Through-holes	φ 0.3 mm × 21 pcs			

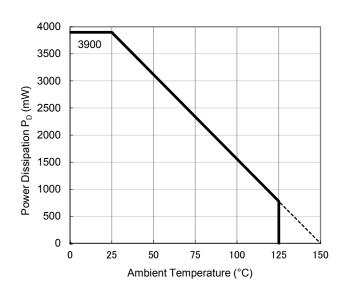
#### **Measurement Result**

 $(Ta = 25^{\circ}C, Tjmax = 150^{\circ}C)$ 

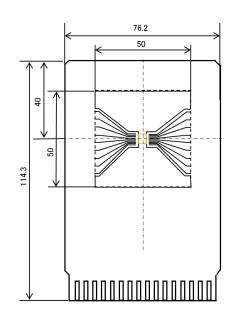
Item	Measurement Result
Power Dissipation	3900 mW
Thermal Resistance (θja)	θja = 32°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 8°C/W

θja: Junction-to-Ambient Thermal Resistance

ψjt: Junction-to-Top Thermal Characterization Parameter

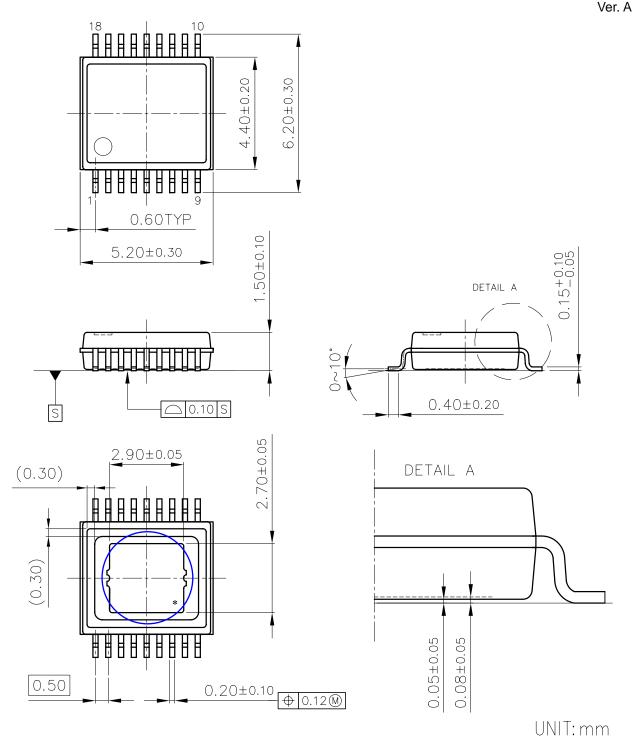


Power Dissipation vs. Ambient Temperature



**Measurement Board Pattern** 

...



**HSOP-18 Package Dimensions** 

**RICOH** 

<sup>\*</sup> The tab on the bottom of the package shown by blue circle is substrate potential (GND). It is recommended that this tab be connected to the ground plane on the board but it is possible to leave the tab floating.



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